



# Product Change Notification

**Change Notification #: 114642 - 00**

**Change Title:** Intel® SSD DC S3510 Series  
(480GB, 800GB, 2.5in SATA 6Gb/s,  
16nm, MLC) 7mm, Generic Single  
Pack,  
Intel® SSD DC S3510 Series  
(480GB, 800GB, 2.5in SATA 6Gb/s,  
16nm, MLC) 7mm, Generic 50  
Pack,  
Intel® SSD DC S3610 Series  
(400GB, 480GB, 800GB, 2.5in  
SATA 6Gb/s, 20nm, MLC) 7mm,  
Generic Single Pack,  
Intel® SSD DC S3610 Series  
(400GB, 800GB, 2.5in SATA  
6Gb/s, 20nm, MLC) 7mm, Generic  
50 Pack,  
Intel® SSD DC S3710 Series  
(400GB, 800GB, 2.5in SATA 6Gb/s,  
20nm, MLC) 7mm, Generic Single  
Pack,  
Intel® SSD DC S3710 Series  
(400GB, 800GB, 2.5in SATA 6Gb/s,  
20nm, MLC) 7mm, Generic 50  
Pack,  
PCN 114642-00, Product Material,  
Adding alternate DRAM to Bill of  
Materials

**Date of Publication:** May 24, 2016

**Key Characteristics of the Change:**

Product Material

**Forecasted Key Milestones:**

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Jun 08, 2016
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## Description of Change to the Customer:

The following changes have been made to the Intel® SSD DC S3510 Series, Intel® SSD DC S3610 Series and Intel® SSD DC S3710 Series products listed on the Products Affected/Intel Ordering Codes table:

1. Add Micron 20nm x4 4G DRAM (IPN: J14739-001) as alternate
2. Current HV3/HV10 (400G/480G/800G) use Micron 30nm x4 4G DRAM (IPN: G69164-001)
3. Current HVSE (480G/800G) use Micron 25nm x4 4G DRAM (IPN: H67056-001)

These changes do not change the form, fit, function, visual or reliability of the product.

## Customer Impact of Change and Recommended Action:

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

## Products Affected / Intel Ordering Codes:

Product Code	MM#
SSDSC2BA400G401	937743
SSDSC2BA400G4	937744
SSDSC2BA800G401	937745
SSDSC2BA800G4	937746
SSDSC2BX400G4	940780
SSDSC2BX400G401	940781
SSDSC2BX480G4	940782
SSDSC2BX480G401	940783
SSDSC2BX800G4	940784
SSDSC2BX800G401	940785
SSDSC2BB480G601	941815
SSDSC2BB480G6	941816
SSDSC2BB800G601	941818
SSDSC2BB800G6	941819

## PCN Revision History:

### Date of Revision:

May 24, 2016

### Revision Number:

00

### Reason:

Originally Published PCN



# Product Change Notification

## 114642 - 00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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